



Materials Declaration Form

IPC Form Type *	1752 Distribute	Version	2
Sectionals *	Material Info Manufacturing Info	Subsectionals *	A-D
<i>* : Required Field</i>			

Supplier Information			
Company Name *	STMicroelectronics	Response Date *	2017-09-13
Contact Name *	Refer to Supplier Comment section		Refer to Supplier Comment section
Authorized Representative *	Rossana Bonaccorso	Representative Title	ADG MD Champion
Representative Phone *	Refer to Supplier Comment section	Representative Email *	Refer to Supplier Comment section
Supplier Comment	Online Technical Support - STMicroelectronics : http://www.st.com/web/en/support/support.html		

Uncertainty Statement


While STMicroelectronics has endeavored to provide information which is accurate and up to date, this document and its contents are provided on a strict 'as is' and 'as available' basis. STMicroelectronics disclaims all warranties, express or implied related to this document and its contents, including but not limited to implied warranties of completeness, truth, accuracy, merchantability, fitness for a particular purpose and non-infringement. ST shall have no responsibility and assumes no liability for any cost, loss or damage of any kind which could arise, directly or indirectly, from the use or inability to use this document and/or its contents.

Legal Statement			
Supplier Acceptance *	true	Legal Declaration *	Standard

Legal Statement

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
STL100N8F7	BSER*OD8RR52	A	3068	2017-09-13
	Amount	UoM	Unit type	ST ECOPACK Grade
	100.00	mg	Each	ECOPACK2

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		 life.augmented
1	260	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
NA	Tin (Sn), matte	Copper Alloy		

Package Designator	Size	Nbr of instances	Shape	
QFN	5-6-0.8	12	Flat	
Comment	Power FLAT 5x6 8L SINGLE			

QueryList : RoHS Directive 2011/65/EU-July 2011 – Annex II amended by Directive 2015/863-April 2015	
Query	Response
1 - Product(s) meets EU RoHS requirement without any exemptions	FALSE
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	FALSE
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	TRUE
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	FALSE
Exemption Id.	Description
7a	Lead in high melting temperature type solders (i.e. lead- based alloys containing 85 % by weight or more lead)

Query : California Prop65 list, dated 27th January 2017			
Query			Response
1 - The product does not contain identified substance from California Prop 65 List, no exposure to consumers is foreseen			FALSE
2 - The product is containing below substance(s) from California Prop 65 List, no exposure to consumers is foreseen			TRUE
Substance	amount in product (mg)	Application	ppm in product
Nickel	0.03	die backside metal	310
Lead	4.41	soft solder	44070

QueryList : REACH-12th January 2017				
Query				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration : note : Substance present with less 0.001mg will not be declared in this document						Mfr Item Name	BSER*OD8RR52									
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)				
Die	Other inorganic materials	1.471	mg	supplier	die	Silicon (Si)	7440-21-3		1.307	mg	888511	13070				
				supplier	metallization	Aluminium (Al)	7429-90-5		0.049	mg	33311	490				
				supplier	metallization	Titanium (Ti)	7440-32-6		0.010	mg	6798	100				
				supplier	Passivation	Silicon Oxide	7631-86-9		0.056	mg	38069	560				
				supplier	back side metallization	Titanium (Ti)	7440-32-6		0.003	mg	2039	30				
				supplier	back side metallization	Nickel (Ni)	7440-02-0		0.031	mg	21074	310				
				supplier	back side metallization	Vanadium (V)	7440-62-2		0.002	mg	1360	20				
				supplier	back side metallization	Silver (Ag)	7440-22-4		0.013	mg	8838	130				
				Leadframe	Copper & its alloys	49.735	mg	supplier	alloy	Copper (Cu)	7440-50-8		48.987	mg	984960	489870
								supplier	alloy	CopperPhosphorous (CuP)	12517-41-8		0.049	mg	986	490
supplier	metallization	Silver (Ag)	7440-22-4						0.699	mg	14054	6990				
Soft solder	Solder	4.764	mg	JIG - R	solder	Lead (Pb)	7439-92-1	7a-Lead in high me	4.407	mg	925063	44070				
				supplier	solder	Tin (Sn)	7440-31-5		0.238	mg	49958	2380				
				supplier	solder	Silver (Ag)	7440-22-4		0.119	mg	24979	1190				
Bonding wires	Other inorganic materials	0.116	mg	supplier	wire	Gold (Au)	7440-57-5		0.116	mg	1000000	1160				
				supplier	mold compound	Silica, vitreous	60676-86-0		32.717	mg	926014	327170				
Encapsulation	Other Organic Materials	35.331	mg	supplier	mold compound	epoxy resin	85954-11-6		1.413	mg	39993	14130				
				supplier	mold compound	phenol resin	26834-02-6		1.060	mg	30002	10600				
				supplier	mold compound	carbon black	1333-86-4		0.141	mg	3991	1410				
				supplier	solder alloy	Tin (Sn)	7440-31-5		0.149	mg	1000000	1490				
Connections coating	Solder	0.149	mg	supplier	solder alloy	Tin (Sn)	7440-31-5		0.149	mg	1000000	1490				
Clip	Copper & its alloys	8.434	mg	supplier	alloy	Copper (Cu)	7440-50-8		8.434	mg	1000000	84340				